

EPTC 2015 - PROGRAM OVERVIEW

Wednesday, 2 nd December 2015 (Professional Development Courses)			
0730 - 0830 hrs	Registration @ Outside Libra, Level 1 (Secretariat Room)		
0830 - 1220 hrs	PDC 1: Fan Out Wafer Level Packaging (FO-WLP) – Innovative Packaging Solutions with Scalability Dr. YOON Seung Wook, STATS ChipPAC, Singapore Aquarius & Pisces, Level 1	PDC 2: Automotive Packaging & its Reliability Requirements Dr. Werner KANERT, Infineon Technologies, Germany Capricorn, Level 1	PDC 3: 3D IC Integration and 3D IC Packaging Dr. John H LAU, ASM Pacific Technology, Hong Kong Gemini, Level 1
	Lunch @ Aquamarine Restaurant, Level 5		
1220 - 1310 hrs	PDC 4: Failure Analysis of 2.5D/3D IC Packages: Fundamental Principles, Applications and Challenges Dr. Yong-Fen HSIEH, MA-tek, Taiwan Aquarius & Pisces, Level 1	PDC 5: Chip Package Interaction (CPI) for Leading Edge (Sub-20nm) Silicon Technology Dr. Shan GAO, GLOBALFOUNDRIES, Singapore Capricorn, Level 1	PDC 6: Adhesion Science & Practice with an Emphasis on Temporary Bonding of Electronics Jared PETTIT, Alex BREWER, Alman LAW and John MOORE, DAETEC, USA Gemini, Level 1
	Lunch @ Aquamarine Restaurant, Level 5		
1730 - 1930 hrs	Panel Session: Packaging Opportunities & Challenges for the Internet of Things @ Taurus / Leo Ballroom, Level 1		

Thursday, 3 rd December 2015					
0730 - 0830 hrs	Registration @ Outside Libra, Level 1 (Secretariat Room)				
0830 - 0835 hrs	Welcome Speech @ Marina Mandarin Ballroom, Level 1 Mr. CHONG Chin Hui, EPTC 2015 General Chair				
0835 - 0855 hrs	Opening Address @ Marina Mandarin Ballroom, Level 1 Jean M. TREWHELLA, IEEE CPMT President Elect				
0855 - 0940 hrs	Keynote Address @ Marina Mandarin Ballroom, Level 1 Panel Level Packaging Technologies as Enabler for Innovative Products Dr. Rolf ASCHENBRENNER, Head of the System Integration & Interconnection Technologies, Fraunhofer IZM				
0940 - 1025 hrs	Keynote Address @ Marina Mandarin Ballroom, Level 1 Foundry Role in Packaging Solutions for Mobile, Datacenter, and IOT Jean M. TREWHELLA, Director of Packaging Technology Interaction, GLOBALFOUNDRIES				
1025 - 1110 hrs	Tea/Coffee Break @ Exhibition & Poster Display Area (Foyer of Marina Mandarin Ballroom, Level 1)				
1110 - 1230 hrs	A1. Advanced Packaging Gemini, Level 1	A2. TSV / Wafer Level Packaging Taurus, Level 1	A3. Interconnection Technologies Leo, Level 1	A4. Wafer / Package level & TSV Testing & Characterization Capricorn, Level 1	A5. Materials & Processes Aquarius & Pisces, Level 1
	Lunch @ Vanda Ballroom, Level 5				
1230 - 1345 hrs	Presentation of EPTC 2014 Best Paper Awards Presentation of IEEE CPMT Certification of Appreciation to EPTC 2015 Organizing Committee				
1345 - 1525 hrs	B1. Electrical Modeling & Simulations Gemini, Level 1	B2. Mechanical Modeling & Simulations Taurus, Level 1	B3. Thermal Characterization & Cooling Solutions Leo, Level 1	B4. Quality & Reliability Capricorn, Level 1	B5. Emerging Technologies Aquarius & Pisces, Level 1
	Tea/Coffee Break @ Exhibition & Poster Display Area (Foyer of Marina Mandarin Ballroom, Level 1)				
1525 - 1550 hrs	C1. Interconnection Technologies Gemini, Level 1	C2. Materials & Processes Taurus, Level 1	C3. Interconnection Technologies Leo, Level 1	C4. Quality & Reliability Capricorn, Level 1	C5. Mechanical Modeling & Simulations Aquarius & Pisces, Level 1
	Tea/Coffee Break @ Exhibition & Poster Display Area (Foyer of Marina Mandarin Ballroom, Level 1)				
1550 - 1800 hrs	Conference Banquet (Venue: Orgo @ Esplanade)				
1830 - 2130 hrs	Conference Banquet (Venue: Orgo @ Esplanade)				

Friday, 4 th December 2015					
0830 - 1010 hrs	D1. TSV / Wafer Level Packaging Gemini, Level 1	D2. Interconnection Technologies Taurus, Level 1	D3. Materials & Processes Leo, Level 1	D4. Quality & Reliability Capricorn, Level 1	D5. Advanced Packaging Aquarius & Pisces, Level 1
1010 - 1040 hrs	Tea/Coffee Break @ Exhibition & Poster Display Area (Foyer of Marina Mandarin Ballroom, Level 1)				
1040 - 1230 hrs	E1. TSV / Wafer Level Packaging Gemini, Level 1	E2. Technical Meeting Taurus, Level 1	E3. Materials & Processes Leo, Level 1	E4. Electrical Modeling & Simulations Capricorn, Level 1	E5. Advanced Packaging Aquarius & Pisces, Level 1
	Lunch @ Vanda Ballroom, Level 5				
1230 - 1345 hrs	Presentation of Appreciation to Invited Papers & Invited Presentation 17th Electronic Packaging Technology Conference Organisation Committee Appreciation 18th Electronic Packaging Technology Conference Introduction				
1345 - 1530 hrs	F1. Interconnection Technologies Gemini, Level 1	F2. Advanced Packaging Taurus, Level 1	F3. Materials & Processes Leo, Level 1	F4. Mechanical Modeling & Simulations Capricorn, Level 1	F5. Quality & Reliability Aquarius & Pisces, Level 1
	Tea/Coffee Break @ Exhibition & Poster Display Area (Foyer of Marina Mandarin Ballroom, Level 1)				
1530 - 1600 hrs	Tea/Coffee Break @ Exhibition & Poster Display Area (Foyer of Marina Mandarin Ballroom, Level 1)				
1600 - 1700 hrs	G1. Advanced Packaging Gemini, Level 1	G2. Technical Meeting Taurus, Level 1	G3. Interconnection Technologies Leo, Level 1	G4. Technical Meeting Capricorn, Level 1	G5. Thermal Characterization & Cooling Solutions Aquarius & Pisces, Level 1
	Tea/Coffee Break @ Exhibition & Poster Display Area (Foyer of Marina Mandarin Ballroom, Level 1)				